



Material Content Data Sheet



Sales Product Name		BSC600N25NS3 G		Issued		19. July 2018		
MA#		MA000680474						
Package		PG-TDSON-8-1		Weight*		122.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	3.62	3.62	36212	36212
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		309	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	copper	7440-50-8	37.762	30.89	30.93	308996	309398
wire	non noble metal	copper	7440-50-8	0.065	0.05	0.05	535	535
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		652	
	plastics	epoxy resin	-	5.660	4.63		46314	
	inorganic material	silicondioxide	60676-86-0	34.119	27.92	32.62	279190	326156
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11879	11879
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1354	1354
solder	noble metal	silver	7440-22-4	0.087	0.07		713	
	non noble metal	tin	7440-31-5	0.070	0.06		570	
	non noble metal	lead	7439-92-1	3.328	2.72	2.85	27235	28518
CLIP plating	noble metal	silver	7440-22-4	1.289	1.06	1.06	10551	10551
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92630	92751
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	copper	7440-50-8	22.292	18.24	18.27	182408	182646
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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